

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced trench Technology
- Excellent $R_{DS(ON)}$ and Switching Performance

Applications

- UPS
- Inverter

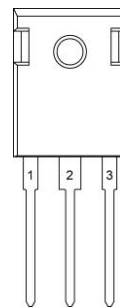
Quick reference

- $V_{DS} = 200\text{ V}$
- $I_D = 150\text{ A}$
- $R_{DS(ON)} \leq 10\text{ m}\Omega$ @ $V_{GS}=10\text{ V}$ (Type: 8.5 m Ω)

Pin Description

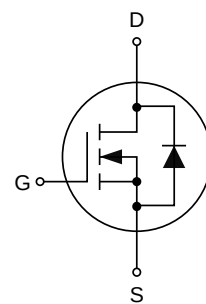
Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

Simplified Outline



Top View
TO-247-3L

Symbol



Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity
KJ4668P	TO-247-3L	KJ4668 XXXXYY	-	-	300

2. Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage	200	V
V_{GS}	Gate-Source Voltage	±30	V
I_D	Continuous Drain Current, $V_{GS}@10\text{ V}$, $T_C=25^\circ\text{C}$	150	A
	Continuous Drain Current, $V_{GS}@10\text{ V}$, $T_C=100^\circ\text{C}$	102	A
I_{DM}	Pulsed Drain Current	450	A
E_{AS}	Single Pulse Avalanche Energy	600	mJ
E_{AR}	Avalanche Energy, Repetitive	150	mJ
I_{AS}	Avalanche Current	90	A
dv/dt	Peak Diode Recovery dv/dt	10.0	V/ns
P_D	Power Dissipation, $T_C=25^\circ\text{C}$ ⁴	750	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	0.45	°C/W

3. Electrical Characteristics (T_J=25°C, unless otherwise noted)

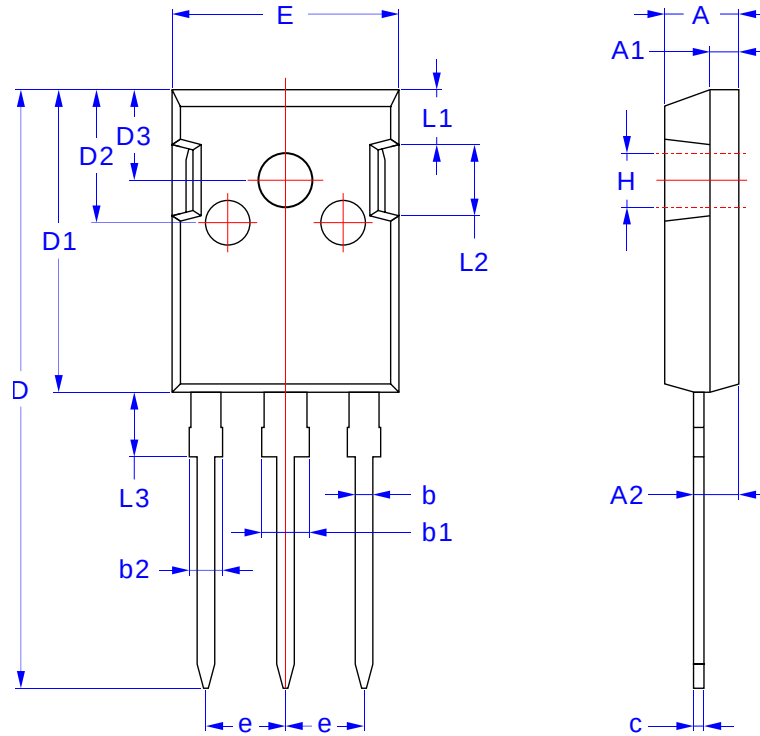
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _D =250 μA	200	220	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200 V, V _{GS} =0 V, T _C =25°C	-	-	1.0	μA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200 V, V _{GS} =0 V, T _C =125°C	-	-	100	μA
I _{GSS}	Gate-body Leakage current	V _{DS} =0 V, V _{GS} =±20 V	-	-	±100	nA
V _{GS(th)}	Gate-Threshold Voltage	V _{DS} =V _{GS} , I _D =250 μA	3.6	4.3	5.0	V
R _{DS(on)}	Drain-Source on-Resistance	V _{GS} =10 V, I _D =80 A	-	8.5	10	mΩ
g _{fs}	Forward Trans conductance	V _{DS} =25 V, I _D =80 A	50	65	-	S
R _g	Total Gate Charge	V _{GS} =0 V, V _{DS} =0 V, f=1 MHz	-	1.3	-	Ω
C _{iss}	Input Capacitance	V _{DS} =50 V, V _{GS} =0 V, f=1 MHz	-	1500 0	-	pF
C _{oss}	Output Capacitance		-	1000	-	
C _{rss}	Reverse Transfer Capacitance		-	420	-	
t _{d(on)}	Turn-on Delay Time	V _{GS} =10 V, V _{DS} =50 V, R _G =2.5 Ω, I _D =80 A	-	90	-	ns
t _r	Turn-on Rise Time		-	140	-	
t _{d(off)}	Turn-off Delay Time		-	220	-	
t _f	Turn-off Fall Time		-	180	-	
Q _g	Total Gate Charge	V _{GS} =10 V, V _{DS} =100 V, I _D =80 A	-	170	-	nC
Q _{gs}	Gate-Source Charge		-	30	-	
Q _{gd}	Gate-Drain Charge		-	50	-	
V _{SD}	Diode Forward Voltage	I _S =80 A, V _{GS} =0 V	-	-	1.2	V
I _S	Continuous Source Current (Body Diode)		-	-	150	A
I _{SM}	Maximum Pulsed Current (Body Diode)		-	-	500	A
t _{rr}	Reverse Recovery Time	I _S =60 A, V _{DD} =50 V, di/dt=100 A/μs	-	220	-	ns
Q _{rr}	Reverse Recovery Charge		-	1.1	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2 OZ copper.
2. The data tested by pulsed, pulse width ≤ 300 μs, duty cycle ≤ 2%
3. The E_{AS} data shows Max. rating. The test condition is T_J=25°C, L=0.3 mH, R_G=25 Ω, V_{DD}=50 V, V_{GS}=10 V
4. The I_S=80 A, di/dt ≤ 100 A/μs, V_{DD} ≤ V_{DS}, Start T_J=25°C
5. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

4. Package Mechanical Data

TO-247-3L



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	4.90	5.10
A1	1.90	2.10
A2	2.00	3.00
b	0.55	0.75
b1	2.50	3.50
b2	1.75	2.50
c	1.20	1.30
D	41.00	42.00
D1	20.00	21.00
D2	8.00	10.00
D3	5.00	6.00
E	15.00	16.00
e	TYP 5.08	
H	3.00	3.50
L1	3.50	4.00
L2	4.75	5.25
L3	4.00	5.00